

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ063N04LS6	**Issued**	4. July 2019
MA#	MA005350248		
Package	PG-TSDSON-8-25	**Weight***	35.35 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.241	0.68	0.68	6826	6826
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		70	
	non noble metal	zinc	7440-66-6	0.010	0.03		278	
	non noble metal	iron	7439-89-6	0.197	0.56		5565	
	non noble metal	copper	7440-50-8	7.988	22.60	23.20	225954	231867
wire	noble metal	gold	7440-57-5	0.029	0.08	0.08	809	809
encapsulation	organic material	carbon black	1333-86-4	0.038	0.11		1082	
	plastics	epoxy resin	-	1.970	5.57		55723	
	inorganic material	silicondioxide	60676-86-0	17.118	48.41	54.09	484196	541001
leadfinish	non noble metal	tin	7440-31-5	0.395	1.12	1.12	11180	11180
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	575	575
solder	non noble metal	tin	7440-31-5	0.008	0.02		222	
	noble metal	silver	7440-22-4	0.010	0.03		277	
	non noble metal	lead	7439-92-1	0.375	1.06	1.11	10594	11093
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001	0.00		26	
	non noble metal	zinc	7440-66-6	0.004	0.01		103	
	non noble metal	iron	7439-89-6	0.073	0.21		2061	
	non noble metal	copper	7440-50-8	2.959	8.37	8.59	83701	85891
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		33	
	non noble metal	zinc	7440-66-6	0.005	0.01		133	
	non noble metal	iron	7439-89-6	0.094	0.27		2658	
	non noble metal	copper	7440-50-8	3.816	10.79	11.07	107934	110758
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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